

Amend the application identified above as follows:

IN THE CLAIMS

Amend claims 1 and 4 as follows:

- sub D1
C1*
1. (Thrice Amended) A semiconductor integrated circuit device comprising:
- a die connected to a ground lead and a power lead;
 - a ground plane connected to the ground lead;
 - an electrically insulating layer which electrically isolates said die and said ground plane;
 - a decoupling capacitor having a first end and a second end, the first end connected to the ground plane and the second end connected to the power lead; and
 - an encapsulating material which encapsulates the die.

- sub D1
C2*
4. (Once Amended) The semiconductor integrated circuit device according to Claim 3, wherein an intra-package wiring substrate comprising wirings for a connecting path between the ground and power leads, bonding pads of the die is disposed between the die and the ground plane, and the decoupling capacitor is connected to the ground plane at one end and the power line of the intra-package wiring substrate at the other end.

Add the following new claims:

- sub D1
C3*
14. The semiconductor integrated circuit device according to Claim 1, wherein the encapsulating material encapsulates the decoupling capacitor and the electrically insulating layer.
15. The semiconductor integrated circuit device according to Claim 14, wherein the encapsulating material encapsulates the ground plane.